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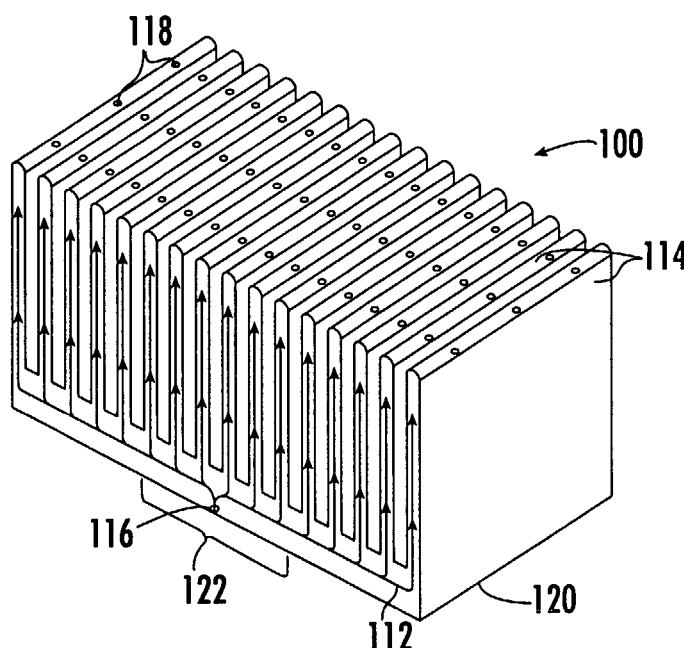
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(54) Title: METHOD OF MOLDING A REINFORCED ARTICLE



(57) Abstract: A method of molding a reinforced article (100) for optimizing heat transfer, electrical conductivity and/or structural integrity is provided. A mold assembly is first provided which is capable of forming an article (100) of a desired configuration, which may include a base (112) and upstanding fins (114). The desired positioning of the filler within the molded article (100) is determined according to the thermal, electrical or structural needs of the article (100). An input gate (116) and output gate vent (118) is formed in the mold assembly to insure positioning of the filler as desired. Polymer, loaded with reinforced filler, is introduced into the mold assembly via the input gate (116). Polymer is positioned in the mold assembly with the reinforcing filler being substantially parallel and aligned with the flow path. A bottom surface (120) of base (112) is provided with flush thermal communication with a heat generating device which may be positioned in the area designated (122).

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